



Do you like news and articles like this?

Then, get it from the **ORIGINAL** source ... **PCB UPDATE** ...
the semi-monthly e-mail newsletter produced by **Circuits Assembly**
and **PCD&M** and circulated to over 40,000 readers.

[CLICK HERE TO READ THE ARTICLE YOU REQUESTED](#)

Reworkable Underfill Encapsulant

CN-1453 is a new, silica-filled reworkable underfill encapsulant used to underfill flip chips, wafer level chip-scale packages (CSPs), CSPs and ball grid array (BGAs). Removal of defective components is accomplished by heating the component and the underfill encapsulant to 220°C. Underfill encapsulant residues are then easily scraped or brushed off. The encapsulant has a viscosity of 7500 cps at room temperature and is capable of flowing 18 mm, with a single-side dispense, in as little as 20 seconds. The encapsulant self-fillets, eliminating the need for seal passes to create complete and symmetrical fillets.

Zymet Inc., East Hanover, NJ
Booth 1363

X-Ray Inspection System

The TIGER (FXS-160.40) x-ray system now offers proprietary True X-Ray Intensity (TXI) control to assist operators in identifying production anomalies with consistent x-ray images. Unlike conventional techniques for maintaining image consistency that control the input level of high-voltage and x-ray tube current, TXI controls the output level of x-ray intensity during the image acquisition process, producing stable, permanent image quality. It also provides steady x-ray intensity after auto-start; long-term stability of x-ray intensity; and constant image contrast and brightness for recurring inspection tasks.

FEINFOCUS, Garbsen, Germany
Booth 1197

Manufacturing Software

The Navipoint Enterprise Performance Suite provides original equipment manufacturers (OEMs) with real-time visibility to operational information so that employees, customers and suppliers can be more responsive. It analyzes and presents enterprise, plant and departmental views of key performance indicators in a personalized portal. The software allows users to take actions through industry specific applications that streamline quoting, schedule sharing and order status tracking. It provides real-time information on product genealogy and supplier performance through a Web browser.

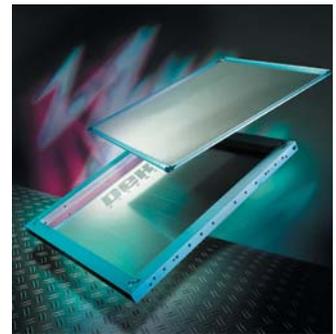
Cimnet Systems Inc., Downers Grove, IL
Booth 2041

Don't miss more products to be featured at APEX in our February APEX Product Spotlight!

Stencil System

VectorGuard is an advanced stencil technology that is easier to handle than conventional stencils. It is surrounded by a thin aluminum extrusion that makes it lighter, and, with the risks from sharp edges eliminated, it enhances operator safety. Its variable foils guarantee print performance and operator safety. The stencil's rigid construction protects the stencil body during handling and, because it does not use an aluminum frame like mesh mounted stencils, offers cost-savings and minimized storage capacity requirements.

DEK International GmbH, Flemington, NJ
Booth 1215



Split Vision Rework Station

The Marksman Intruder offers placement and reflow for all types of boards and components, including ball grid array (BGA) and lead-free applications. The station features a convection panel preheat system available in 900 W, 1600 W and 2400 W heater configurations that can duplicate original manufacturing temperature parameters. The system incorporates the P-300 controller with each profile containing up to 16 segments of ramp/soak combined with four integrated real-time thermocouples for profile development.

A.P.E., Key Largo, FL
Booth 1909



Tape Feeders

The fast-loading Agilis feeder is now available for 12 and 16 mm tapes. In addition to the new feeder sizes, MYDATA is introducing a new magazine with linear motion, which offer smooth, high speed and precision feeding, for 0201s or smaller components. In place of a traditional feeder wheel to pull the tape, the new drive features a solenoid tape-grabbing mechanism with auto adjust capability.

MYDATA Automation Inc., Rowley, MA
Booth 857



Lead-Free Solder Paste

Multicore LF320 is a lead-free solder paste optimized for reflow in air on a range of printed circuit board (PCB) assembly applications. Reflow profiles may also be extended with nitrogen. The paste requires a minimum peak reflow temperature of only 229°C. With a print speed range of 25 to 100 mm. (1.0 to 4.0 in.) and an abandon time of up to two hours, the paste offers excellent wetting on a range of surface finishes. The solder paste has been formulated to provide high resistance to slump and solder balling.

Henkel Loctite Corp., Industry, CA
Booth 1826

